This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claims 1-38 (Canceled).

39. (New) A compound connector device for connecting at least one of a first type of I/O electronic package having contacts on a leading edge thereof, and a second type of I/O electronic package different from said first type and having a leading edge and two major surfaces and having contacts on one of said two major surfaces thereof, comprising:

a connector section;

first guiding structure connected to and extending lengthwise from the connector section and defining at least a first storage space for receiving the first type of I/O electronic package; the connector section having a contact array for connecting with the first contacts of the first type of I/O electronic package to be inserted in the first storage space; and

second guiding structure affixed to the first guiding structure, and defining at least a second storage space for receiving the second type of I/O electronic package, the second guiding structure having contact terminals thereon different from the contact array of said connector section for connecting with the contacts of the second type of I/O electronic package to be inserted in the second storage space;

wherein the first storage space and the second storage space are substantially coextensive.

40. (New) The compound connector device as set forth in Claim 39, wherein:

said first type of I/O electronic package is a PCMCIA card; and

said second type of I/O electronic package is a smart card.

41. (New) The compound connector of claim 39, wherein said leading edge of said first type of I/O electronic package and said leading edge of said second type of I/O electronic package lie in substantially the same plane.

42. (New) The compound connector according to claim 41, wherein said plane is adjacent said connector section.

43. (New) The compound connector device according to claim 40, wherein said smart card is positioned above said PCMCIA card in said compound connector device.

44. (New) The compound connector device as set forth in Claim 43 wherein said second guiding structure includes a printed circuit board positioned as a top wall of said connector device.

45. (New) The compound connector device as set forth in Claim 44 wherein said second contact terminals protrude downwardly from said printed circuit board into said second storage space.

46. (New) The compound connector device as set forth in Claim 40, wherein the second guiding structure comprises a connection for electrically connecting the second guiding structure to the first guiding structure.

47. (New) The compound connector device as set forth in Claim 46, wherein the connection is a flexible cable.

48. (New) The compound connector device as set forth in Claim 39, further comprising:

a first ejector provided on the first guiding structure and being operable to eject the first type of I/O electronic package from the first storage space; and

a second ejector provided on the second guiding structure and being operable to eject the second type of I/O package from the second storage space;

wherein said first ejector is mechanically different from said second ejector.

49. (New) A compound connector device for connecting a first I/O electronic package having a leading edge and first type of contacts and a second I/O electronic package having a leading edge and a second type of contacts different from said first type of contacts, comprising:

a connector section for connecting said compound connector to an external electronic system;

first guiding structure extending lengthwise from the connector section and defining at least a first storage space for receiving the first I/O electronic package; the connector section having a contact array for connecting with the first type of contacts of the first I/O electronic package to be inserted in the first storage space; and

second guiding structure affixed to the first guiding structure, and defining at least a second storage space for receiving the second I/O electronic package, the second guiding structure having contact terminals thereon for connecting with the second type of contacts of the second I/O electronic package to be inserted in the second storage space;

said second I/O electronic package is positioned above said first I/O electronic package in said connector device; and

said second guiding structure includes a printed circuit board positioned as a top wall of said connector device.

50. (New) The compound connector device according to claim 49, wherein said first I/O electronic package is different from said second I/O electronic package besides for having different contacts.

51. (New) The compound connector device according to claim 50, wherein said first I/O electronic package is a PCMCIA card and said second I/O electronic package is a smart card.

52. (New) The compound connector device according to claim 51, wherein said smart card is positioned above said PCMCIA card in said compound connector device.

53. (New) The compound connector of claim 49, wherein said leading edge of said first type of I/O electronic package and said leading edge of said second type of I/O electronic package lie in substantially the same plane.

54. (New) The compound connector according to claim 53, wherein said plane is adjacent said connector section.

55. (New) A compound connector device including a memory card connector and a smart card connector, the compound connector device comprising:

a connector section;

a first guiding structure connected to and extending lengthwise from the connector section, the first guiding structure comprising first and second spaced apart sidewalls to define a first storage space for receiving a memory card; and

a second guiding structure comprising a base coextensive with and affixed to each of the first and second spaced apart sidewalls, and a plate spaced apart from and facing the base to define a second storage space for receiving a smart card.

56. (New) The compound connector device according to claim 55, wherein the base is a printed circuit board.

57. (New) The compound connector device according to claim 55, wherein the second guiding structure further comprises a separately formed guiding plate extending from the plate in a direction opposing the connector section.

58. (New) A compound connector device for connecting two I/O electronic packages, the compound connector device comprising:

a connector section;

a first guiding structure connected to and extending lengthwise from the connector section and defining a first storage space for receiving a first I/O electronic package; and

a second guiding structure comprising a base affixed to the first guiding structure, and a series of individual plate members that are collectively spaced apart from and facing the base to define a second storage space for receiving a second I/O electronic package.

59. (New) The compound connector device according to claim 58, wherein the series of individual plate members includes a plate and a guiding plate extending therefrom.

60. (New) The compound connector device according to claim 59, wherein the guiding plate is substantially parallel to the plate.

61. (New) The compound connector device according to claim 58, wherein connector section, the first guiding structure, and first storage space define a memory card connector.

62. (New) The compound connector device according to claim 61, wherein the second guiding structure and the second storage space define a smart card connector.